

VI TELEFILTER**Filter specification****TFS 471 B 1/4****Measurement condition**

Ambient temperature: 23 °C
 Input power level: 0 dBm
 Terminating impedances:
 input: 50 Ω
 output: 50 Ω

Construction and pin connection (see page 2)

Characteristics**Remark:**

Reference level for the relative attenuation a_{rel} of the TFS 471 B is the minimum of the pass band attenuation a_{min} . The minimum of the pass band attenuation a_{min} is defined as the insertion loss a_e . The centre frequency f_0 is the arithmetic mean value of the upper and lower frequencies at the 3 dB filter attenuation level relative to the insertion loss a_e . The nominal frequency f_N is fixed on 471,55 MHz without tolerance. The given values for the relative attenuation a_{rel} have to be reached at the frequencies given below also if the centre frequency f_0 is shifted due to the temperature coefficient of frequency TC_f in the operating temperature range and due to a production tolerance for the centre frequency f_0 .

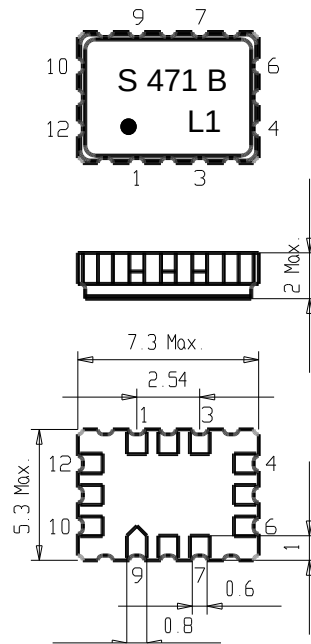
D a t a		typ. value	Variation/ Limitation
Insertion loss (Reference level)	$a_e = a_{min}$	2,5 dB	max. 3,5 dB
Nominal frequency	f_N		471,55 MHz
Centre frequency	f_0	471,55 MHz	
1 dB - bandwidth	BW	6,1 MHz	min. 200 kHz
Relative attenuation	a_{rel}		
$f_N \pm 21$ MHz		65 dB	min. 55 dB
$f_N \pm 41$ MHz		75 dB	min. 65 dB
Temperature coefficient of the frequency	TC_f	-36,1 ppm/K	
Operating temperature range		- 10 °C ... + 60 °C	

Generated :

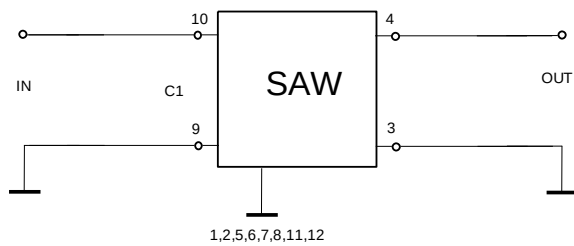
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VI TELEFILTER**Filter specification****TFS 471 B 2/4****Construction and pin connection**

- | | |
|----|------------------|
| 1 | Ground |
| 2 | Ground |
| 3 | Output RF Return |
| 4 | Output |
| 5 | Package Ground |
| 6 | Ground |
| 7 | Ground |
| 8 | Ground |
| 9 | Input RF Return |
| 10 | Input |
| 11 | Package Ground |
| 12 | Ground |

50 Ω test circuit

VI TELEFILTER**Filter specification****TFS 471 B 3/4****Stability characteristics**

After the following tests the filter shall meet the whole specification:

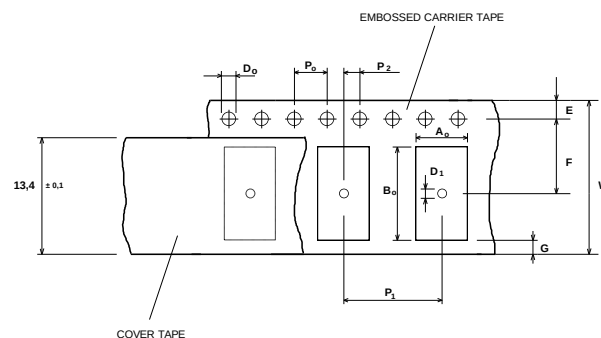
1. Shock: 100g, 18 ms, half sine wave, 3 shocks each plane;
DIN IEC 68 T2 - 27
2. Vibration: 10 Hz to 500 Hz, 0.35 mm amplitude, 5g; 2 hours for 3 planes;
DIN IEC 68 T2 - 6
3. Damp heat: 90 % to 95 % rel. humidity, 40 °C, 10 days;
IEC Pub. 68 - 2 - 3
4. Resistance to solder heat (Reflow): 260 °C for 10 sec;

Packing

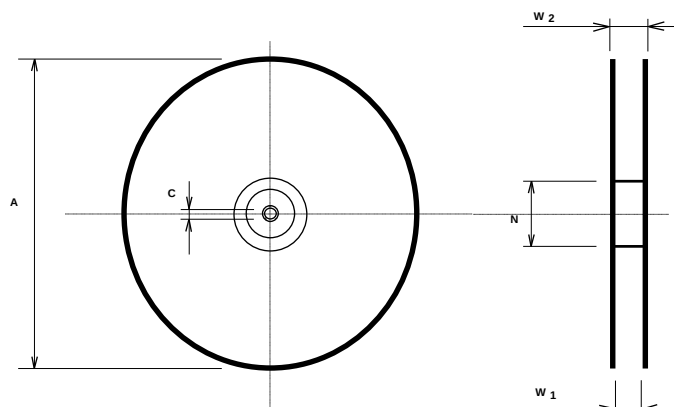
Tape & Reel: IEC 286 - 3, with exception of value for N and minimum bending radius;
tape type II, embossed carrier tape with top cover tape on the upper side;
max. pieces of filters per reel: 3000

Tape (all dimensions in mm)

W	: 16 ± 0,3
Po	: 4 ± 0,1
Do	: 1,5 ± 0,5
D1	: 1,5 ± 0,5
E	: 1,75 ± 0,1
F	: 7,5 ± 0,1
G (min)	: 0,75
P2	: 2 ± 0,05
P1	: 8 ± 0,1
D1(min)	: 1,5
Ao	: 5,4 ± 0,1
Bo	: 7,4 ± 0,1

**Reel (all dimensions in mm):**

A	: 330
W1	: 16,4 +2
W2 (max)	: 22,4
N (min)	: ≥ 90
C	: 13 ± 0,25



The minimum bending radius is 45 mm. The mounting surface of the filters faces the bottom side of the embossed carrier tape. The marking of the filters is able to read if the view is directed on the upper side of the carrier tape with the sprocket holes on the right side of the tape.

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VI TELEFILTER**Filter specification****TFS 471 B 4/4****Air reflow temperature conditions**

1st and 2nd air reflow profile

Name:	pre-heating periods	main-heating periods	peak temperature
Temperature:	150 °C - 170 °C	over 200 °C	255 °C ± 5 °C
Time:	60 sec. - 90 sec.	20 sec. - 25 sec.	

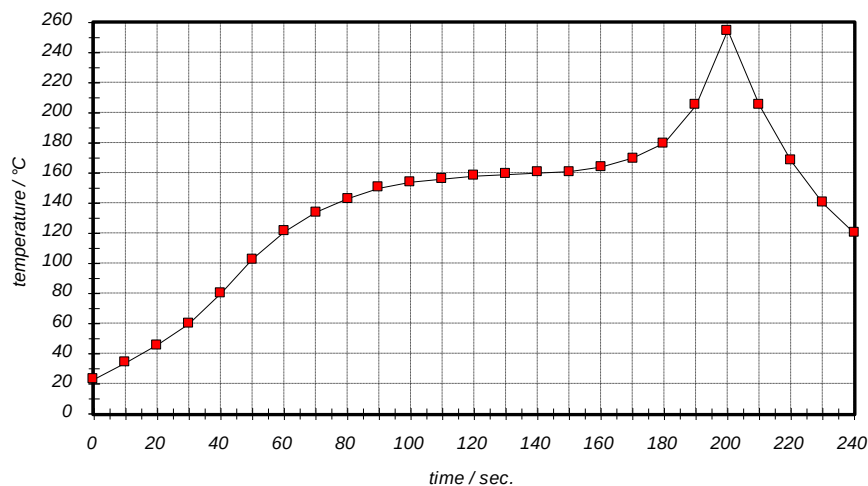
Chip-mount air reflow profile

Table for temperature vs. time during the air reflow process

Tolerance of temperatures: ± 5 °C

<u>time / sec.</u>	<u>temperature / °C</u>	<u>time / sec.</u>	<u>temperature / °C</u>
0	23	140	160
10	34	150	161
20	46	160	164
30	60	170	170
40	80	180	180
50	103	190	205
60	121	195	230
70	134	200	255
80	143	205	230
90	150	210	205
100	154	215	180
110	156	220	165
120	158	230	140
130	159	240	120